maXTouch 1664-node Touchscreen Controller
Product Brief

Description
The mXT1664T3 2.0 uses a unique charge-transfer acquisition engine to implement Microchip’s patented capacitive sensing method. Coupled with a state-of-the-art CPU, the entire touchscreen sensing solution can measure, classify and track a number of individual finger touches with a high degree of accuracy in the shortest response time. The mXT1664T3 2.0 allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

maXTouch® Adaptive Sensing Touchscreen Technology
- Up to 32 X (transmit) lines and 52 Y (receive) lines for use by touchscreen.
- A maximum of 1664 nodes can be allocated to the touchscreen.
- Touchscreen size of 15.6 inches (16:10 aspect ratio), assuming a sensor electrode pitch of 6.5 mm. Other sizes are possible with different electrode pitches and appropriate sensor material.
- Multiple touch support with up to 16 concurrent touches tracked in real time.
- Dual-boot OS support for Microsoft® Windows® and Android™.

Touch Sensor Technology
- Discrete/out-cell support including glass and PET film-based sensors.
- Support for standard (for example, Diamond) and proprietary sensor patterns (review of designs by Microchip or a Microchip-qualified touch sensor module partner is recommended).

Front Panel Material
- Works with PET or glass, including curved profiles (configuration and stack-up to be approved by Microchip or a Microchip-qualified touch sensor module partner).
- Glass 0.4 mm to 4.5 mm (dependent on screen size, touch size, configuration and stack-up).
- Plastic 0.2 mm to 2.2 mm (dependent on screen size, touch size, configuration and stack-up).

Touch Performance
- Moisture/Water Compensation
  - No false touch with condensation or water drop up to 22 mm diameter.
  - One-finger tracking with condensation or water drop up to 22 mm diameter.
- Glove Support
  - Multiple-finger glove touches up to 1.5 mm thickness (subject to stack-up design).
  - Single-finger glove touch up to 5 mm thickness (subject to stack-up design).
- Mutual capacitance and self capacitance measurements supported for robust touch detection.
- Noise suppression technology to combat ambient, charger, and power-line noise.
  - Up to 240 VPP between 1 Hz and 1 kHz sinusoidal waveform.
  - Up to 20 VPP between 1 kHz and 1 MHz sinusoidal waveform.
- Stylus Support
  - Supports passive stylus with 1.5 mm contact diameter, subject to configuration, stack-up, and sensor design.
- Scan Speed
  - Up to 250 Hz reporting rate for one finger (subject to configuration).
  - Typical report rate for 16 touches ≥100 Hz (subject to configuration).
  - Initial touch latency <10 ms for first touch from idle (subject to configuration).
  - Configurable to allow for power and speed optimization.

Enhanced Algorithms
- Lens bending algorithms to remove display noise.
- Touch suppression algorithms to remove unintentional large touches, such as palm.
- Palm Recovery Algorithm for quick restoration to normal state.
Power Saving
• Programmable timeout for automatic transition from active to idle states
• Pipelined analog sensing detection and digital processing to optimize system power efficiency

Application Interfaces
• I²C slave with support for Standard mode (up to 100 kHz), Fast mode (up to 400 kHz), Fast-mode Plus (up to 1 MHz), High Speed mode (up to 3.4 MHz)
• USB HID interface for Microsoft Windows 8.x and later versions
• HID-I²C interface for Microsoft Windows 8.x and later versions
• Interrupt to indicate when a message is available
• SPI Debug Interface to read the raw data for tuning and debugging purposes

Power Supply
• Digital (Vdd) 3.3 V nominal
• Digital I/O (VddIO) 3.3 V nominal
• Analog (AVdd) 3.3 V nominal
• High voltage external X line drive (XVdd) up to 10 V

Packages
• 136-ball UFBGA 7 × 7 × 0.6 mm, 0.5 mm pitch
• 162-ball UFBGA 10 × 5 × 0.6 mm, 0.5 mm pitch

Operating Temperature
• −40°C to +85°C
## PIN CONFIGURATION

### 0.1 136-ball UFBGA

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Top View
1.0 PACKAGING INFORMATION

1.1 136-ball UFBGA 7 x 7 x 0.6 mm

NOTE  For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging
1.2 162-ball UFBGA 10 × 5 × 0.6 mm

**NOTE** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

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**DRAWINGS NOT SCALED**

**TOP VIEW**

**SIDE VIEW**

**COMMON DIMENSIONS**

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**TITLE**

7M, 162-ball - 19x9 4P array (+ 2 balls),
0.5mm pitch, 10x5x0.6mm
Ultra Thin Fine-Pitch Ball Grid Array Package (UFBGA)

**02/13/2015**
APPENDIX A:  REVISION HISTORY

Revision A (August 2018)
Initial edition for firmware revision 2.0 – Release
MXT1664T3 2.0

PRODUCT IDENTIFICATION SYSTEM

The table below gives details on the product identification system for maXTouch devices. See “Orderable Part Numbers” below for example part numbers for the mXT1664T3.

To order or obtain information, for example on pricing or delivery, refer to the factory or the listed sales office.

<table>
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<th>Tape and Reel Option</th>
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<td>QTP, SQTP, Code or Special Requirements</td>
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Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. See “Orderable Part Numbers” below or check with your Microchip Sales Office for package availability with the Tape and Reel option.

Orderable Part Numbers

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<td>ATMXT1664T3-CCUR035</td>
<td>2.0.AA</td>
<td>162-ball UFBGA 10 × 5 × 0.6 mm, RoHS compliant Industrial grade; not suitable for automotive characterization</td>
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Atmel SL Code

An SL (QS) code was required on Atmel purchase orders, but is no longer used by Microchip. The SL code has been replaced by the 3-digit QTP code suffix on all Microchip industrial grade orderable part numbers.

The legacy Atmel SL (QS) code for mXT1664T3 2.0.AA is QS976.
Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV

ISO/TS 16949
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Fax: 34-91-708-08-91

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Worldwide Sales and Service